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## Reduction of Electrical Resistance of Nanometer-Thick CoSi<sub>2</sub> Film on CaF<sub>2</sub> by Pseudomorphic Growth of CaF<sub>2</sub> on Si(111)

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1.9-nm-thick epitaxial metal (CoSi<sub>2</sub>) films were grown on relaxed or pseudomorphic CaF<sub>2</sub>/Si(111) and their electrical resistance was measured. It was found that the electrical resistance of the CoSi<sub>2</sub> film on pseudomorphic CaF<sub>2</sub> was about half of that on relaxed CaF<sub>2</sub>. This result can be attributed to the improved flatness and crystalline quality of the CoSi<sub>2</sub> by using of pseudomorphic CaF<sub>2</sub> instead of relaxed CaF<sub>2</sub> due to the flat pseudomorphic CaF<sub>2</sub> surface and the small lattice mismatch between CoSi<sub>2</sub> and pseudomorphic CaF<sub>2</sub>.

**KEYWORDS:** CoSi<sub>2</sub>/CaF<sub>2</sub> heterostructure on Si, very thin metal film, pseudomorphic CaF<sub>2</sub>, relaxed CaF<sub>2</sub>

Metal-insulator (M-I) heterostructure is a very attractive material system for ultra-high speed and multifunctional quantum devices due to the high carrier density of the metal, the low dielectric constant of the insulator and the very large conduction band discontinuity at the heterointerface.<sup>1)</sup> We developed an epitaxial growth technique<sup>2)</sup> for nanometer-thick multilayer structures, with CoSi<sub>2</sub> and CaF<sub>2</sub> as the metal and insulator, respectively, because they have a fluorite lattice structure and are closely lattice-matched to Si, with mismatches of -1.2% and +0.6%, respectively, at room temperature. Using this technique we demonstrated the primitive action of a hot electron transistor, a resonant tunneling transistor and a quantum interference transistor.<sup>3-5)</sup> In these devices, reduction of electrical resistance in the very thin epitaxial metal film is essential for the improvement of device characteristics.<sup>4,6)</sup> This resistance depends strongly on the flatness and crystalline quality of the CaF<sub>2</sub> layer under the metal film.

In this study, nanometer-thick epitaxial metal (CoSi<sub>2</sub>) films were grown on relaxed or pseudomorphic CaF<sub>2</sub>/Si(111) and their electrical resistance was measured. It was found that the electrical resistance of the CoSi<sub>2</sub> film on pseudomorphic CaF<sub>2</sub> was about half of that on relaxed CaF<sub>2</sub>.

The epitaxial growth system was equipped with a liquid-nitrogen shroud and was evacuated by ion pump with a background pressure of less than  $1 \times 10^{-9}$  Torr. The CaF<sub>2</sub> layer was deposited from a solid source using a graphite crucible. The CoSi<sub>2</sub> layer was deposited from solid sources of Si and Co using electron-gun evaporators. A Si substrate with (111) orientation was chemically cleaned and a protective oxide layer was grown. Then, the substrate was loaded into the growth chamber through a load lock and heated to 750°C with exposure to a Si beam to evaporate the protective oxide layer. This process yielded a well developed 7×7 RHEED pattern.

In the epitaxial growth, 15-nm-thick relaxed or pseudomorphic CaF<sub>2</sub> layer was grown on Si(111) at first. The relaxed CaF<sub>2</sub> was grown at a constant temperature of 650°C, while the pseudomorphic CaF<sub>2</sub> was grown at 770°C for the first 0.6 nm and at 200°C for the remainder of the growth period.<sup>7)</sup>

The  $\text{CoSi}_2$  was grown on these  $\text{CaF}_2$  layers using a two-step growth technique:<sup>2)</sup> firstly, solid-phase epitaxy of the Si layer at 300°C, followed by Co deposition at less than 800°C. Finally, a 5-nm-thick layer of  $\text{CaF}_2$  was grown by ionized beam epitaxy at 200°C to protect the fabrication of the measurement samples.<sup>2)</sup> The wafers were not annealed after growth in this experiment.

Figure 1 shows the surface image of the protective  $\text{CaF}_2$  layer using scanning electron microscopy (SEM). The sample containing pseudomorphic  $\text{CaF}_2/\text{Si}(111)$  is flatter than the sample containing relaxed  $\text{CaF}_2/\text{Si}(111)$ . This may be because larger step-bunching occurs in the relaxed  $\text{CaF}_2$ , due to its high growth temperature (650°C), compared to that occurring in the pseudomorphic  $\text{CaF}_2$  (200°C).

Ohmic contact to the  $\text{CoSi}_2$  metal layer was made to measure electrical resistance using Au/Cr electrodes using photolithography and selective wet chemical etching processes.<sup>2)</sup> The diameter of each electrode was 20  $\mu\text{m}$  and the distance between the electrodes was 1 mm. The resistance was measured at room temperature.

Figure 2 shows the measured distribution of the resistivity of the  $\text{CoSi}_2$  layers. Average values of resistivity were 60 and 28  $\mu\Omega\text{cm}$  on relaxed and pseudomorphic  $\text{CaF}_2$ , respectively. The electrical resistivity of the  $\text{CoSi}_2$  layer on pseudomorphic  $\text{CaF}_2$  was about half of that on relaxed  $\text{CaF}_2$ , and was comparable to that of an annealed  $\text{CoSi}_2$  layer on relaxed  $\text{CaF}_2$ .<sup>2)</sup>

This result is interpreted as follows. The flatness of the  $\text{CoSi}_2$  layer on  $\text{CaF}_2$  is better in the sample with pseudomorphic  $\text{CaF}_2$ , which is deduced from the surface image of the top layer shown above. Moreover, the  $\text{CoSi}_2$  on pseudomorphic  $\text{CaF}_2$  may have better crystalline quality because of the smaller lattice mismatch between  $\text{CoSi}_2$  and  $\text{CaF}_2$  (-1.2%) compared to that between  $\text{CoSi}_2$  and relaxed  $\text{CaF}_2$  (-1.8%). Due to these characteristics the resistivity of the  $\text{CoSi}_2$  layer was reduced by the use of pseudomorphic  $\text{CaF}_2$ .

In conclusion, 1.9-nm-thick epitaxial metal ( $\text{CoSi}_2$ ) films were grown on relaxed or pseudomorphic  $\text{CaF}_2/\text{Si}(111)$  and their electrical resistance was measured. Electrical resistance of the  $\text{CoSi}_2$  film on pseudomorphic  $\text{CaF}_2$  was about half of that on relaxed  $\text{CaF}_2$ . This result can be attributed to the improved flatness and crystalline quality of the  $\text{CoSi}_2$  due to the use of pseudomorphic  $\text{CaF}_2$  instead of relaxed  $\text{CaF}_2$ .

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**Figures:**

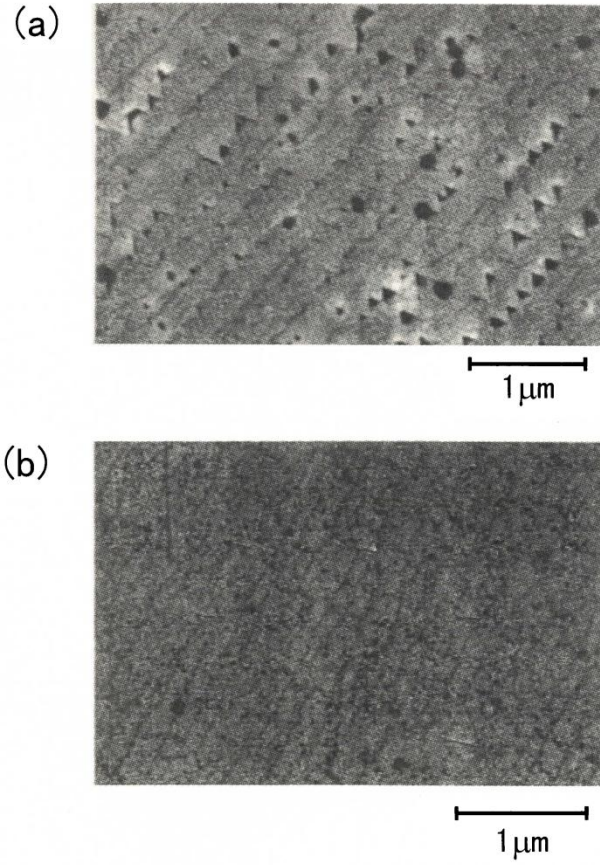


Fig.1. SEM surface view of samples. (a) CaF<sub>2</sub>/CoSi<sub>2</sub>/ relaxed CaF<sub>2</sub>/Si(111) and (b) CaF<sub>2</sub>/CoSi<sub>2</sub>/pseudomorphic CaF<sub>2</sub>/Si(111).

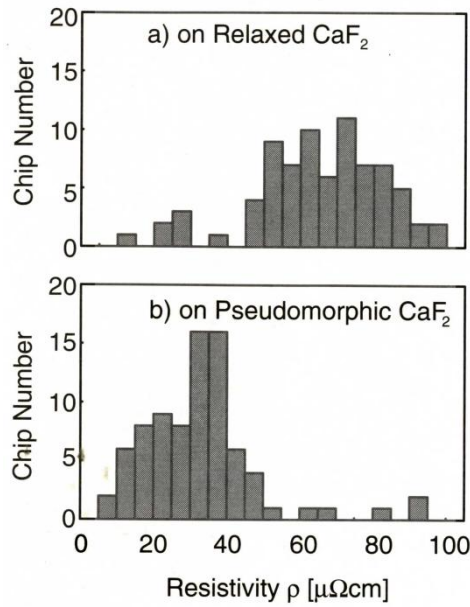


Fig.2. Distribution of resistivity of 1.9-nm-thick CoSi<sub>2</sub> films on (a) relaxed and (b) Pseudomorphic CaF<sub>2</sub>.